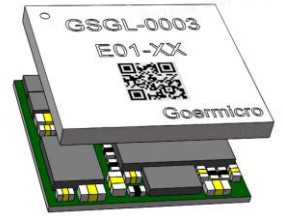


# GSGL-0003

## [ Ultra-Small, Ultra-Low Power GNSS SiP Module ]

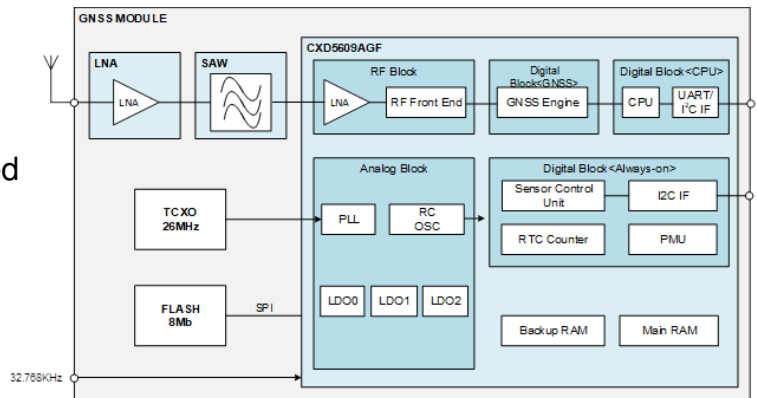
### Fully Integrated GNSS SiP Solution for Wearable & Portable Devices

Goermicro GSGL-0003 module is based on System in Package (SiP) technology which consists of a SONY CXD5609AGF, LNA, SAW Filter, FLASH, TCXO and some other passive components. All these components are integrated in a tiny package via 47-pins  $5.3 \times 4.9 \times 0.94\text{mm}^3$  LGA with sputter technology to achieve EMI shielding, 30% size reduction on Axis XY compare to the normal PCB design.



### Features

- A multi-GNSS receiver for GPS, GIONASS, SBAS, QZSS, BeiDou and Galileo
- RF Front-Ends, 26MHz TCXO Integrated
- Package Size:  $5.3 \times 4.9 \times 0.94\text{mm}^3$
- Flash: 8Mbit
- Supply Voltage Range : 1.71V ~ 1.89V
- Operating Temp. Range :  $-30 \sim +85^\circ\text{C}$



### Applications

- Smart phones
- Tablets
- Mobile accessories
- Wearables
- Drones
- Toys

### Descriptions

Item	Value	Unit	Remark	
<b>Current Consumption</b>				
Acquisition	14	mA	R&S-SMBV100B 8KHz~6GHZ @Temp. 25°C, Shielding Room	
Tracking	7	mA		
Idle	1.8	mA		
<b>Position Accuracy</b>				
2DRMS	1.0	m		
CNO @-130dBm	42	dBHz		
<b>Sensitivity</b>				
Cold Acquisition	-148	dBm		
Tracking	-162	dBm		
Re-Acquisition	-157	dBm		
<b>Time-To-First-Fix (TTFF)@-130dBm</b>				
Cold Start	<30	s		
Hot Start	<2	s		

